

[0023] Various modifications can be made to the present invention without departing from the apparent scope hereof.

IT IS CLAIMED:

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1. Process for wave soldering components onto a printed circuit board comprising the steps of:

- a. providing on a printed circuit board opposing spacer pads adjacent to lead holes for the leads of a component for slightly spacing a base of a component away from said printed circuit board; and,
- b. wave soldering leads of a component to said printed circuit board.

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